

What is claimed is:

1. A method for making a marking grid for radiographic imaging, comprising the steps of:

providing a substrate attached to a releasable backing, the substrate having a front side
5 and a back side, the back side being releasably attached to the releasable backing, and the
releasable backing defining a plurality of apertures spaced relative to each other along at least
one marginal portion thereof;

registering the substrate and backing with at least one of a tool for cutting the substrate
and a tool for applying a material that is at least partially radiopaque to the substrate by engaging
10 the apertures in the backing with at least one rotatably driven drive member registered with said
at least one tool; and

moving the substrate and backing relative to the at least one tool by rotatably driving the
drive member and moving the tool relative to the substrate to perform at least one of the
following additional steps: (a) applying a material that is at least partially radiopaque to the
15 substrate at predetermined locations on the substrate, and (b) forming apertures in the substrate
extending between the predetermined locations of radiopaque material on the substrate.

2. The method of claim 1, wherein the substrate is attached to the releasable backing
by a pressure sensitive adhesive coating the back side of the substrate.

3. The method of claim 2, wherein the releasable backing defines a plurality of holes
on first and second marginal portions thereof.

4. The method of claim 3, wherein the plurality of holes on the first marginal portion are spaced equidistantly from each other, and the plurality of holes on the second marginal portion are spaced equidistantly from each other.

5. A method for making a marking grid for radiographic imaging, comprising the steps of:

providing a substrate attached to a releasable backing, the substrate having a front side and a back side, the back side being releasably attached to the releasable backing, and the
5 releasable backing defining a plurality of apertures spaced relative to each other along at least one marginal portion thereof;

registering the substrate and backing with a first tool head for applying a material to the substrate that is at least partially radiopaque by engaging the apertures in the backing with drive means registered with said first tool head;

10 applying a material that is at least partially radiopaque to the substrate at predetermined locations on the substrate using the first tool head;

moving the substrate and backing relative to the first tool head by driving the drive means to move the substrate relative to the first tool head;

registering the substrate and backing with a second tool head for cutting the substrate by
15 engaging the apertures in the backing with drive means registered with said second tool head;

forming apertures in the substrate extending between the predetermined locations of radiopaque material on the substrate by cutting the substrate using the second tool head; and moving the substrate and backing relative to the second tool head by driving the drive means to move the substrate relative to the second tool head.

6. The method of claim 5, wherein the second tool head is a die cutter.

7. The method of claim 5, wherein the drive means comprises sprockets rotatably mounted on a base having a plurality of sprocket pins which are received within the apertures of the releasable backing;

a motor drivingly connected to the sprockets; and

5 a control unit electrically coupled to the motor to control the movement of the marking grid through the apparatus.

8. The method of claim 5, further comprising the steps of:

registering the substrate and backing with a third tool head for printing indicia or other markings on the front side of the substrate by engaging the apertures in the backing with drive means registered with said third tool head;

5 printing indicia or other markings on the front side of the substrate at predetermined locations using the third tool head; and

moving the substrate and backing relative to the third tool head by driving the drive means to move the substrate relative to the third tool head.